PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6807413

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ZVI OR-BACH	07/11/2021
BRIAN CRONQUIST	07/10/2021
DEEPAK SEKAR	07/12/2021

RECEIVING PARTY DATA

Name:	MONOLITHIC 3D INC.
Street Address:	1662 COVE POINT RD
City:	KLAMATH FALLS
State/Country:	OREGON
Postal Code:	97601

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17372776

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4088399533
Email: Brian@MonolithIC3D.com
Correspondent Name: BRIAN CRONQUIST
Address Line 1: 1662 COVE POINT RD
Address Line 4: KLAMATH FALLS, OREGON 97601

ATTORNEY DOCKET NUMBER:	MONOLITHIC3D15HBVN_40LWC1
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/Brian Cronquist/
DATE SIGNED:	07/12/2021

Total Attachments: 3
source=MonolithIC3D15HBVN_40LWc1_Assignment_Zvi signed#page1.tif
source=MonolithIC3D15HBVN_40LWc1_Assignment_Deepak signed#page1.tif
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ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

METHOD FOR PRODUCING A 3D SEMICONDUCTOR MEMORY DEVICE AND STRUCTURE

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about July 11, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

pp. 7/6 '23

DATE on 07 / 11 / 2021

(**Zvi**		**Or-Bach**)
First Name	Middle Initial	Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and United States Patent Application entitled:

METHOD FOR PRODUCING A 3D SEMICONDUCTOR MEMORY DEVICE AND STRUCTURE

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about July 11, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 07 / 12 / 2021

(**Deepak**		**Sekar**)
First Name	Middle Initial	Last Name

ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in Klamath Falls, Oregon;** have made a certain invention, and United States Patent Application entitled:

METHOD FOR PRODUCING A 3D SEMICONDUCTOR MEMORY DEVICE AND STRUCTURE

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about July 11, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 10 July 2021

(**Brian** First Name | Middle Initial | **Cronquist**) Last Name